

PHYSICAL VAPOR DEPOSITION (PVD) PROCESS OVERVIEW

Who should attend?

This course is designed for those individuals in the semiconductor industry who require the knowledge of the basic principles of the PVD process.

Course Benefits

Increase knowledge of:
Process Fundamentals
Integration of process in wafer fabrication
Process measurement techniques

Course Objective Summary

- Describe the overall chip manufacturing process
- Describe the Endura PVD system
- Describe the PVD chamber and the PVD process
- Describe the two applications and the metals used in the PVD process
- Describe the Preclean chamber and the Preclean process
- Describe the Metal Interconnect Layer deposition
- Describe the IMP chamber and the IMP process
- Describe the Tungsten Plug Fill deposition
- Describe the SiP chamber and the SiP process
- Describe the Copper Deposition process

Course Modules

1. PVD Process Overview

Registration Information

Prerequisites: None

Course Length: 1 Hour

Course Type: Web-based Training

Course Number: TRNWEB-203

To enroll or for more information on our products and services, please call our registrar at one of the numbers below or go to www.appliedtraining.com.

- 1-800-468-8888, option 4 (United States)
- 1-512-272-0027 (International)

Computer System Requirements:

Attending this course requires a Windows 98, NT, 2000 or XP computer using Internet Explorer 5.5 or higher. 128MB RAM or higher and high-speed Internet access is also highly recommended. For the audio portion of the class, headsets or speakers and a sound card are required.